503633929 01/05/2016

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tse-Wei Chung	12/18/2015
Tsung-Hui Chou	12/18/2015
Che-Hung Lin	12/18/2015
Shao-Wei Lu	12/16/2015
Hsiao-Pei Lin	12/16/2015

RECEIVING PARTY DATA

Name:	Powerchip Technology Corporation
Street Address:	NO.12, Li-Hsin Road 1, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14987777	

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU **Address Line 1:** P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	LKSP0197USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	01/05/2016

Total Attachments: 10 source=2450428#page1.tif source=2450428#page2.tif source=2450428#page3.tif

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PATENT REEL: 037405 FRAME: 0001

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PATENT REEL: 037405 FRAME: 0002

Title of Invention:

INTEGRATED BIO-SENSOR WITH NANOCAVITY AND FABRICATION METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	filed on	, or	
☐ PCT international application	number	filed on	_
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this decisionment of not more than five (5	claration is punishable) years, or both.	
In consideration of the payment by	Powerchip Technology Corporation	having a postal ad	dress of
NO.12, Li-Hsin Road 1, Hsinc	hu Science Park, Hsinchu 3	300, Taiwan, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of which is h	ereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified application of invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pai any continuations, continuation-	hich are disclosed in the tent to be obtained for said in-part, divisions, renewals.	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	nce has been or will be made	e or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	icts ;
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have here	lication, said invention and said lecessary or desirable to carry out	_etters Patent and said	of signing)
Note: An application data sheet (PTC inventive entity, must accompany thi	D/SB/14 or equivalent), including s form. Use this form for <u>each ad</u>	naming the entire ditional inventor.	

Page 1 of 10

NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Tse-Wei Chung

Date:

DEC 18 2015

Signature:

The War Church

Page 2 of 10

Title of Invention:

INTEGRATED BIO-SENSOR WITH NANOCAVITY AND FABRICATION METHOD THEREOF

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hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbrand n this assignment;	ce has been or will be	made or	
further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne N WINTNESS WHEREOF, I have he	lication, said invention and said Lecessary or desirable to carry out t	etters Patent and said he proposes thereof.	l Date of signing)	
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Page 3 of 10

NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tsung-Hui Chou Date: DEC 1 8 2015

Tsung-Hui Chou Signature:

Page

F#NPO-P0002E-US1201

DSB0-104U034257

Title of Invention:

INTEGRATED BIO-SENSOR WITH NANOCAVITY AND FABRICATION METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or			
☐ United States application number		filed on	, or
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The above-identified application was	s made or authorized to be made	by me.	
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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all improvements wation and, in and to, all Letters Par r any continuations, continuation	which are disclosed in the attent to be obtained for said in-part, divisions, renewals.	EE
I hereby covenant that no assignme entered into which would conflict wit	nt, sale, agreement or encumbra h this assignment;	nce has been or will be made	or
I further covenant that ASSIGNEE wand documents relating to said invertions and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interf	legal equivalents as may be erence, litigation proceeding	ts
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	plication, said invention and said ecessary or desirable to carry out	Letters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTo nventive entity, must accompany thi	O/SB/14 or equivalent), including is form. Use this form for <u>each ac</u>	naming the entire	

Page 5 of 10

NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Che-Hung Lin Date:

DEC 1 8 2015

Signature: Che- Hung Lin

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NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

Title of Invention:

INTEGRATED BIO-SENSOR WITH NANOCAVITY AND FABRICATION METHOD THEREOF

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The above-identified application was	made or authorized to be made b	by me.	,	
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I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements wh tion and, in and to, all Letters Pate any continuations, continuation-ir	nich are disclosed in ent to be obtained fo n-part, divisions, ren	the r said ewals	
l hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbrand n this assignment;	ce has been or will b	e made or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said Lecessary or desirable to carry out t	etters Patent and sa	id (Date of signing)	
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including n s form. Use this form for <u>each add</u>	naming the entire itional inventor.		

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NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Shao-Wei Lu

Date:

2015/12/16

Signature:

Shao-Wei Lu

Page 8 of 10

Title of Invention:

INTEGRATED BIO-SENSOR WITH NANOCAVITY AND FABRICATION METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application number filed		on	, or	
□ PCT international application number f		file	ed on	
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I believe that I am the original invent application.	or or an original joint inv	entor of a claime	ed invention in the	е
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made i isonment of not more th	n this declaration an five (5) years,	ո is punishable or both.	
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NO.12, Li-Hsin Road 1, Hsincl	nu Science Park, Hs	sinchu 300, Ta	– liwan, R.O.C.	*
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and I hereby covenant that no assignment entered into which would conflict with I further covenant that ASSIGNEE wand documents relating to said inventions and accessible to I and will te	ASSIGNEE and the succeed to any and all improve tion and, in and to, all Let any continuations, control as to Letters Patent and this assignment; ill, upon its request, be patent and and said Letters Patent and the sasignment.	cessors and assi- ements which are etters Patent to be inuation-in-part, ny reissue or re- ncumbrance has provided promptly tent and legal ed	e disclosed in the pe obtained for sa divisions, renew examination there been or will be not with all pertiner suivalents as ma	e aid rals, reof. made or nt facts
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representatives any and all papers, is maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention a cessary or desirable to desira	and said Letters for carry out the properties 2615. 12.	Patent and said poses thereof. (D	Pate of signing)
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Page 9 of 10

NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Hsiao-Pei Lin Date: Date:

Signature: Hsian - Pei Vin

Page 10 of 10

NPO#LKS-P0197-USA:0 CUST#PT.AP-1586

F#NPO-P0002E-US1201 DSB0-104U034257

PATENT REEL: 037405 FRAME: 0012